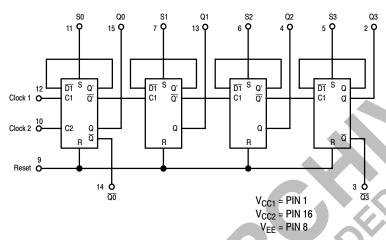
Binary Counter

The MC10178 is a four-bit counter capable of divide-by-two, divide-by-four, divide-by-eight or a divide-by-sixteen function.

Clock inputs trigger on the positive going edge of the clock pulse. Set and Reset inputs override the clock, allowing asynchronous "set" or "clear." Individual Set and common Reset inputs are provided, as well as complementary outputs for the first and fourth bits. True outputs are available at all bits.

- $P_D = 370 \text{ mW typ/pkg (No Load)}$
- f_{toggle}=150 MHz (typ)
- t_r , $t_f = 2.7$ ns typ (20%–80%)

LOGIC DIAGRAM



TRUTH TABLE

INPUTS								OUTF	PUTS	
R	S0	S1	S2	S3	C1	C2	Q0	Q1	Q2	Q3
Н	L	L	L	L	X	X	L	L	L	L
L	Н	Н	Н	Н	X	X	H	Н	Н	Н
L	L	L	L	L	Н	Х		No C		
L	L	L	L	L	Χ	H		No C	ount	
L	L	L	L	L	*		L	L	L	L
L	L	L	L	L	*		Н	L	L	L
L	L	L	L	L	*		L	Н	L	L
L	L	L	L	L	*		Н	Н	L	L
L	L	L	-		*		L	L	Н	L
L	L	L	5		*		H	L	H	L
L	Ŀ	Ŀ	43		*		L	H	Н	L
L	L			L	*		H	H	H	Н
L	-		<u> </u>	_	*	*	H	L	L	Н
-		4	_	L	*	*	L	Н	L	H
Ī		1	Ī	ī	*	*	H	H	-	H H
Ĺ		L	L	L	*	*	L	L	H	Н
L	Ł	L	L	L	*	*	Н	L	Н	Н
L	L	L	L	L	*	*	L	Н	Н	Н
L	L	L	L	L	*	*	Н	Н	Н	Н
** V _{IL} -	** V _{IH} Clock transition from V _{IL} to V _{IH} may be applied to C ₁ or C ₂ or both for									



ON Semiconductor

http://onsemi.com





PDIP-16 P SUFFIX CASE 648

CASE 620

MC10178P

O AWLYYWW

1

1

1

AWLYYWW



PLCC-20 FN SUFFIX CASE 775 10178 AWLYYWW

A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

DIP PIN ASSIGNMENT

		V		<u> </u>	
V_{CC1}	1		16	Ш	V_{CC2}
Q3	2		15		Q0
Q3	3		14		$\overline{Q0}$
Q2	4		13		Q1
S3	5		12		CLOCK 1
S2	6		11		S0
S1	7		10		CLOCK 2
V_{EE}	8		9	Ы	RESET

Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

ORDERING INFORMATION

Device	Package	Shipping
MC10178L	CDIP-16	25 Units / Rail
MC10178P	PDIP-16	25 Units / Rail
MC10178FN	PLCC-20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

		Pin		Test Limits -30°C +25°C				1		
0 1		Under	-			+25°C			5°C	١.,
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	U
Power Supply Drain Current	I _E	8		97			88		97	m
Input Current	I _{inH}	12 11		390 350			245 220		245 220	μ
		9		650			410		410	
	I _{inL}	*	0.5		0.5			0.3		μ
Output Voltage Logic 1	V _{OH}	14 15	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	٧
Output Voltage Logic 0	V _{OL}	14 15	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	
Threshold Voltage Logic 1	V _{OHA}	3	-1.080		-0.980			-0.910	C	V
		14 15	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		
Threshold Voltage Logic 0	V _{OLA}	3	1.000	-1.655	0.000		-1.630	0.010	-1.595	V
Timoshola voltago Logio o	VOLA	14		-1.655			-1.630		-1.595	•
		15		-1.655			-1.630	V	-1.595	
Switching Times (50 Ω Load)										1
Propagation Clock Input Delay		15 13	1.4 1.9	5.0 9.4	1.5 2.0	3.5 6.0	4.8 9.2	1.5 2.0	5.3 9.8	
Delay	t ₁₂₋₁₃₋ t ₁₂₊₄₋	4	2.9	12.3	3.0	8.5	12.0	3.0	12.8	
	t ₁₂₋₃₊	3	3.9	14.9	4.0	11.0	14.5	4.0	15.5	
Rise Time (20 to 80%)	t ₁₅₊	15	1.1	4.7	1.1	2.5	4.5	1.1	5.0	
Fall Time (20 to 80%)	t ₁₅₋	15	1.1	4.7	1.1	2.5	4.5	1.1	5.0	
Set Input	t ₁₁₋₁₅₊	15	1.4	5.2	1.5		5.0	1.5	5.5	
Reset Input	t ₉₋₁₅₊	15	1.4	5.2	1.5		5.0	1.5	5.5	
Counting Frequency Individually test each input ap	f _{count}	15	125		125	150		125		N
OENICE		CO	test.							

ELECTRICAL CHARACTERISTICS (continued)

					TEST VOI	TAGE VALU	JES (Volts)		
		@ Test Te	mperature	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	
		-30°C		-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
Pin		TEST V							
Characteri	Characteristic		Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain C	Current	ΙE	8	9				8	1, 16
Input Current		I _{inH}	12	12				8	1, 16
			11 9	11 9				8 8	1, 16 1, 16
		I _{inL}	*		*			8	1, 16
Output Voltage	Logic 1	V _{OH}	14 15	9 11				8 8	1, 16 1, 16
Output Voltage	Logic 0	V _{OL}	14 15	11 9				8 8	1, 16 1, 16
Threshold Voltage	Logic 1	V _{OHA}	3 14 15			5 11 9		8 8 8	1, 16 1, 16 1, 16
Threshold Voltage	Logic 0	V _{OLA}	3 14 15				5 11 9	8 8 8	1, 16 1, 16 1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay	Data Input	t ₁₂₊₁₅₊	15		\ \	12	15	8	1, 16
		t _{12–13} – t _{12+4–}	13 4			12 12	13 4	8 8	1, 16 1, 16
		t ₁₂₋₃₊	3			12	3	8	1, 16
Rise Time	(20 to 80%)	t+	15			12	15	8	1, 16
Fall Time	(20 to 80%)	t→	15			12	15	8	1, 16
Set Input		t ₁₁₋₁₅₊	15			11	15	8	1, 16
Reset Input	1	t ₉₋₁₅₊	15			9	15	8	1, 16
Counting Frequency		f _{count}	15			12	15	8	1, 16

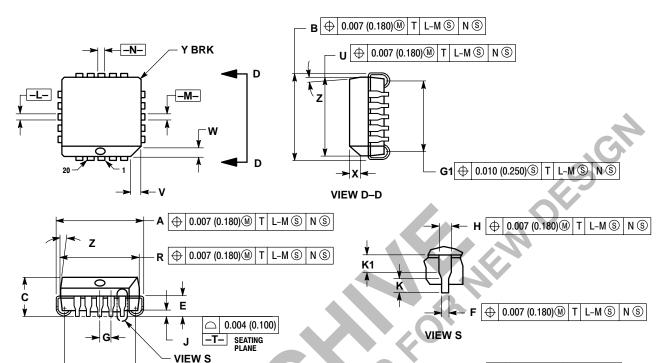
^{*} Individually test each input applying V_{IL} to input under test.

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- OTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

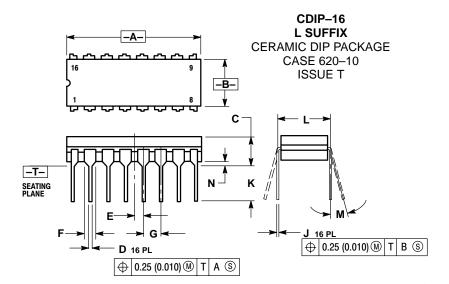
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS



NOTES:

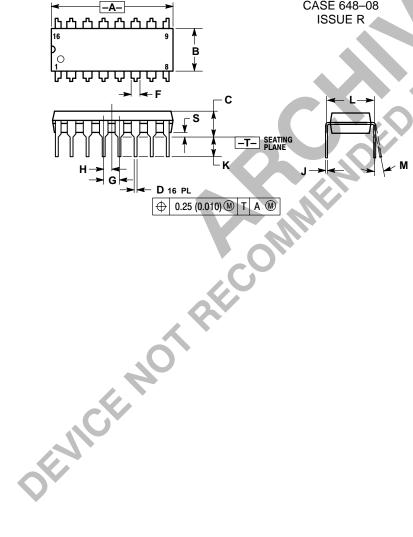
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
 BODY.

	INC	HES	MILLIMETERS					
DIM	MIN	MAX	MIN	MAX				
Α	0.750	0.785	19.05	19.93				
В	0.240	0.295	6.10	7.49				
C		0.200		5.08				
D	0.015	0.020	0.39	0.50				
E	0.050	BSC	1.27 BSC					
F	0.055	0.065	1.40	1.65				
G	0.100	BSC	2.54 BSC					
Н	0.008	0.015	0.21	0.38				
K	0.125	0.170	3.18	4.31				
L	0.300	BSC	7.62 BSC					
M	0 °	15°	0 °	15°				
N	0.020	0.040	0.51	1.01				

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.740	0.770	18.80	19.55		
В	0.250	0.270	6.35	6.85		
C	0.145	0.175	3.69	4.44		
D	0.015	0.021	0.39	0.53		
F	0.040	0.70	1.02	1.77		
G	0.100	BSC	2.54 BSC			
Н	0.050	BSC	1.27 BSC			
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295	0.305	7.50	7.74		
M	0°	10 °	0°	10 °		
S	0.020	0.040	0.51	1.01		

Notes



Notes





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